



### N-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>C</sub> = +25°C	
001/	6mΩ @ V <sub>GS</sub> = 10V	80A	
60V	8.5mΩ @ V <sub>GS</sub> = 4.5V	70A	

# **Description and Applications**

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Brushless DC motor controls
- DC-DC converters
- Load switches

## **Features and Benefits**

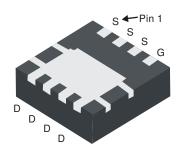
- Low R<sub>DS(ON)</sub> Ensures On-State Losses are Minimized
- Excellent Q<sub>gd</sub> × R<sub>DS(ON)</sub> Product (FOM)
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- 100% Unclamped Inductive Switching, Test in Production Ensures More Reliable and Robust End Application
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMT6007LFGQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

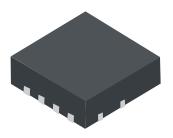
### **Mechanical Data**

- Package: PowerDI<sup>®</sup>3333-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminal Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.034 grams (Approximate)

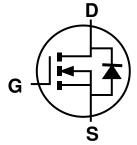
### PowerDI3333-8







Top View



**Equivalent Circuit** 

## **Ordering Information** (Note 4)

Part Number	Dookogo	Packing		
Part Number	Package	Qty.	Carrier	
DMT6007LFGQ-7	PowerDI3333-8	2,000	Tape & Reel	
DMT6007LFGQ-13	PowerDI3333-8	3,000	Tape & Reel	

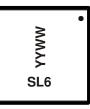
Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



# **Marking Information**

Site1:



SL6 = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 23 = 2023) WW = Week Code (01 to 53)

Site2:



SL6 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 3 = 2023)W = Week (ex: a = Week 27, z Represents Week 52 and 53)

X = Internal Code (ex: U = Monday)

# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V <sub>DSS</sub>	60	V	
Gate-Source Voltage		Vgss	±20	V
Continuous Dunis Courset (Nata F) V 10V	$T_A = +25$ °C $T_A = +70$ °C	I <sub>D</sub>	15 12	А
Continuous Drain Current (Note 5) V <sub>GS</sub> = 10V	$T_C = +25^{\circ}C$ $T_C = +70^{\circ}C$	lo	80 65	А
Maximum Continuous Body Diode Forward Current (Note 6)	ls	80	Α	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	80	Α	
Avalanche Current, L = 0.1mH	I <sub>AS</sub>	20	А	
Avalanche Energy, L = 0.1mH	Eas	20	mJ	

## **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	$P_{D}$	2.2	W
Thermal Resistance, Junction to Ambient (Note 5)		R <sub>0JA</sub>	55	°C/W
Total Power Dissipation (Note 6)	T <sub>C</sub> = +25°C	PD	62.5	W
Thermal Resistance, Junction to Case (Note 6)		Rejc	2	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

5.  $R_{\theta JA}$  is determined with the device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.  $R_{\theta JC}$  is guaranteed by design Notes: while  $R_{\theta JA}$  is determined by the user's board design.

6. Short duration pulse test used to minimize self-heating effect.



# **Electrical Characteristics** (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BVDSS	60		_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		1	1	μA	$V_{DS} = 48V$ , $V_{GS} = 0V$	
Gate-Source Leakage	Igss		l	±100	nA	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.8		2	٧	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance		- 4.5	4.5	6	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	
Static Dialii-Source Off-nesistance	RDS(ON)	_	6.5	8.5	11122	$V_{GS} = 4.5V, I_D = 15A$	
Forward Transconductance	GFS		100	_	S	$V_{DS} = 5V, I_{D} = 20A$	
Diode Forward Voltage	V <sub>SD</sub>	_	0.9	1.2	V	V <sub>G</sub> S = 0V, I <sub>S</sub> = 20A	
DYNAMIC CHARACTERISTICS (Note 8)				•			
Input Capacitance	Ciss		2090			V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V, f = 1MHz	
Output Capacitance	Coss		746	_	pF		
Reverse Transfer Capacitance	Crss	_	38.5	_			
Gate Resistance	Rg	_	0.59	_	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	19.3	_		V <sub>DS</sub> = 30V, I <sub>D</sub> = 20A	
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	41.3	_	0		
Gate-Source Charge	Qgs		6.0	_	nC		
Gate-Drain Charge	Qgd		8.8	_			
Turn-On Delay Time	t <sub>D(ON)</sub>		5.7	_		V <sub>DD</sub> = 30V, V <sub>GS</sub> = 10V,	
Turn-On Rise Time	tR		4.3	_			
Turn-Off Delay Time	tD(OFF)		23.4	_	ns	$I_D = 20A$ , $R_G = 3\Omega$	
Turn-Off Fall Time	t <sub>F</sub>		9.7	_			
Body Diode Reverse Recovery Time	trr		35.4	_	ns		
Body Diode Reverse Recovery Charge	Qrr	_	38.2	_	nC	IF = 20A, di/dt = 100A/µs	

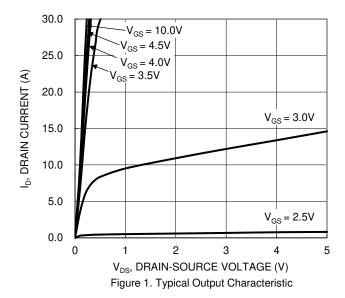
Notes:

<sup>7.</sup> Short duration pulse test used to minimize self-heating effect.

<sup>8.</sup> Guaranteed by design. Not subject to product testing.







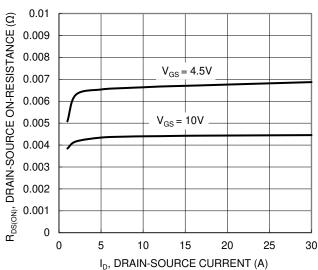


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

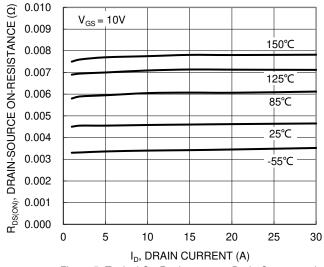


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

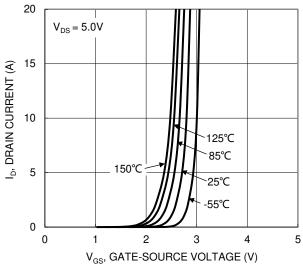


Figure 2. Typical Transfer Characteristic

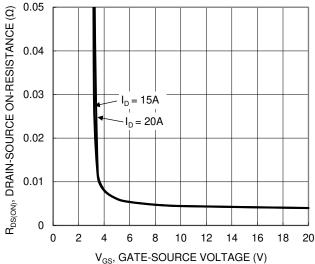


Figure 4. Typical Transfer Characteristic

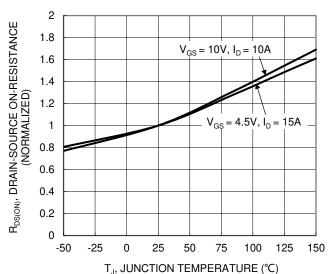
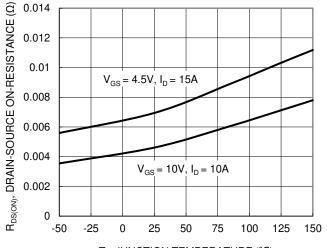
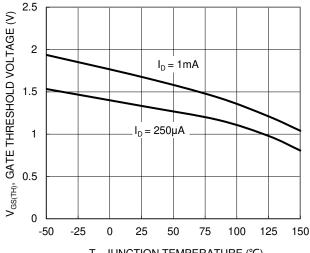


Figure 6. On-Resistance Variation with Temperature

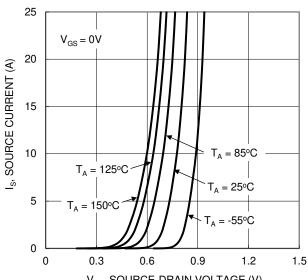




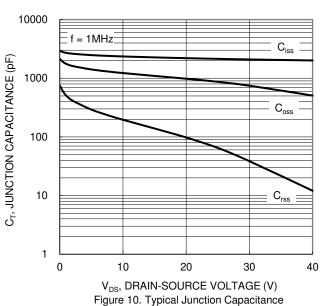
 $T_{\rm J},$  JUNCTION TEMPERATURE (°C) Figure 7. On-Resistance Variation with Temperature



 $\mathsf{T_J},\mathsf{JUNCTION}$  TEMPERATURE (°C) Figure 8. Gate Threshold Variation vs. Junction Temperature



 $\rm V_{SD},$  SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current



R<sub>DS(ON)</sub> Limited =100µs 100 10 P<sub>W</sub> =10ms 1 =100ms P<sub>w</sub> =1s  $T_{J(Max)} = 150^{\circ}C$   $T_A = 25^{\circ}C$ 0.1 Single Pulse  $P_W = 10s$ DUT on 1\*MRP Board  $V_{GS} = 10V$ 0.01

Figure 12. SOA, Safe Operation Area

1000 **DRAIN CURRENT (A)** ے 0.1 100 V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V)

 $V_{DS} = 30V, I_{D} = 20A$ 5 10 15 20 25 30 35 40 45  $Q_q$  (nC) Figure 11. Gate Charge

10

9

8

7 6

5

4

3

2

1

0

0



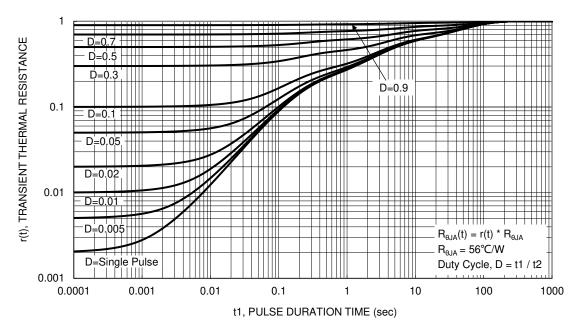


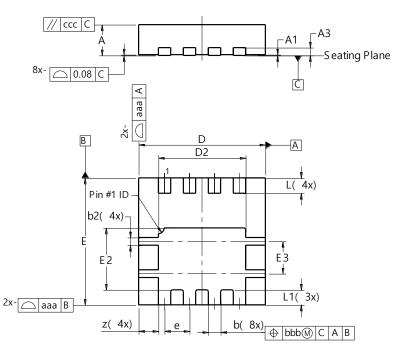
Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### PowerDI3333-8

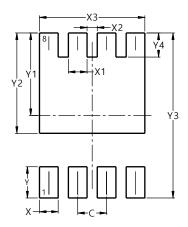


PowerDI3333-8					
Dim	Min	Max	Тур		
Α	0.75	0.85	0.80		
A1	0.00	0.05	0.02		
A3	_	_	0.203		
b	0.27	0.37	0.32		
b2	_	_	0.20		
D	3.25	3.35	3.30		
D2	2.22	2.32	2.27		
Е	3.25	3.35	3.30		
E2	1.56	1.66	1.61		
E3	0.79	0.89	0.84		
е	_	0.65			
L	0.35	0.45	0.40		
L1	-	_	0.39		
z	0.515				
aaa	0.25				
bbb	0.10				
CCC	0.10				
All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### PowerDI3333-8



Dimensions	Value (in mm)		
С	0.650		
X	0.420		
X1	0.420		
X2	0.230		
Х3	2.370		
Υ	0.700		
Y1	1.850		
Y2	2.250		
Y3	3.700		
Y4	0.540		



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